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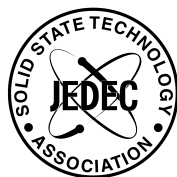
Integrated Circuit Thermal Test Method Environmental Conditions - Forced Convection (Moving Air)

JESD51-6

MARCH 1999

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JEDEC Solid State Technology Association



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**INTEGRATED CIRCUIT THERMAL TEST METHOD
ENVIRONMENTAL CONDITIONS - FORCED CONVECTION (MOVING AIR)**

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INTEGRATED CIRCUIT THERMAL TEST METHOD ENVIRONMENTAL CONDITIONS - FORCED CONVECTION (MOVING AIR)

(From JEDEC Board Ballot JCB-98-103, under the cognizance of the JC-15.1 Committee on Thermal Characterization.)

1 Scope

This standard specifies the environmental conditions for determining thermal performance of an integrated circuit device in a forced convection environment when mounted on a standard test board. The thermal resistance measured using this document is $R_{\theta JMA}$ or θ_{JMA} . This methodology is not meant to and will not predict the performance of a device in an application-specific environment.

2 Normative references

The following standards contain provisions that, through reference in this text, constitute provisions of this standard. At the time of publication, the editions indicated were valid. All standards are subject to revision, and parties to agreements based on this standard are encouraged to investigate the possibility of applying the most recent editions of the standards indicated below.

JESD51, "Methodology for the Thermal Measurement of Component Packages (Single Semiconductor Devices)". This is the overview document for this series of specifications.

JESD51-1, "Integrated Circuit Thermal Measurement Method - Electrical Test Method".

JESD51-2, "Integrated Circuit Thermal Test Method Environmental Conditions - Natural Convection (Still Air)".

JESD51-3, "Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages".

JESD51-4, "Thermal Test Chip Guideline (Wire Bond Type Chip)"

JESD51-7, "High Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages"

3 Definitions, symbols, and abbreviations

Refer to the documents JESD51, JESD51-1 and JESD51-2 for a general list of terminology.